

BC639; BCP56; BCX56

80 V, 1 A NPN medium power transistors

Rev. 08 — 22 June 2007

Product data sheet

1. Product profile

1.1 General description

NPN medium power transistor series.

Table 1. Product overview

Type number ^[1]	Package			PNP complement
	NXP	JEITA	JEDEC	
BC639 ^[2]	SOT54	SC-43A	TO-92	BC640
BCP56	SOT223	SC-73	-	BCP53
BCX56	SOT89	SC-62	TO-243	BCX53

[1] Valid for all available selection groups.

[2] Also available in SOT54A and SOT54 variant packages (see [Section 2](#)).

1.2 Features

- High current
- Two current gain selections
- High power dissipation capability

1.3 Applications

- Linear voltage regulators
- Low-side switches
- MOSFET drivers
- Amplifiers

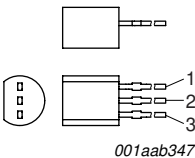
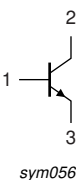
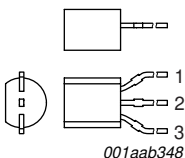
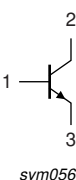
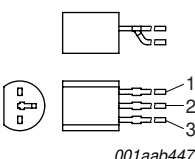
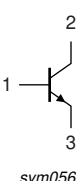
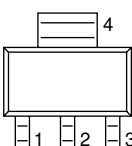
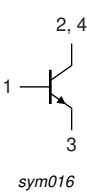
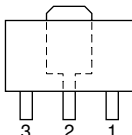
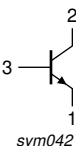
1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	80	V
I_C	collector current		-	-	1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	1.5	A
h_{FE}	DC current gain	$V_{CE} = 2$ V; $I_C = 150$ mA	63	-	250	
	h_{FE} selection -10	$V_{CE} = 2$ V; $I_C = 150$ mA	63	-	160	
	h_{FE} selection -16	$V_{CE} = 2$ V; $I_C = 150$ mA	100	-	250	

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
SOT54			
1	base		
2	collector		
3	emitter		
SOT54A			
1	base		
2	collector		
3	emitter		
SOT54 variant			
1	base		
2	collector		
3	emitter		
SOT223			
1	base		
2	collector		
3	emitter		
4	collector		
SOT89			
1	emitter		
2	collector		
3	base		

3. Ordering information

Table 4. Ordering information

Type number ^[1]	Package		
	Name	Description	Version
BC639 ^[2]	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BCP56	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223
BCX56	SC-62	plastic surface-mounted package; collector pad for good heat transfer; 3 leads	SOT89

[1] Valid for all available selection groups.

[2] Also available in SOT54A and SOT54 variant packages (see [Section 2](#) and [Section 9](#)).

4. Marking

Table 5. Marking codes

Type number	Marking code
BC639	C639
BC639-10	C63910
BC639-16	C63916
BCP56	BCP56
BCP56-10	BCP56/10
BCP56-16	BCP56/16
BCX56	BH
BCX56-10	BK
BCX56-16	BL

5. Limiting values

Table 6. Limiting values

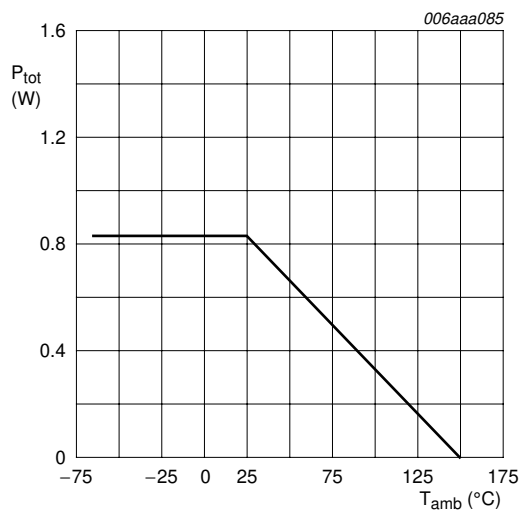
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	100	V
V_{CEO}	collector-emitter voltage	open base	-	80	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current		-	1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	1.5	A
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	0.2	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C			
		BC639	[1] -	0.83	W
		BCP56	[1] -	0.64	W
			[2] -	0.96	W
		BCX56	[1] -	0.5	W
			[2] -	0.85	W
			[3] -	1.25	W
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

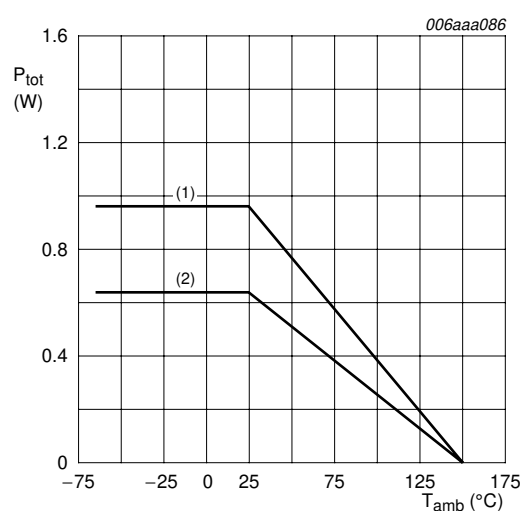
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².



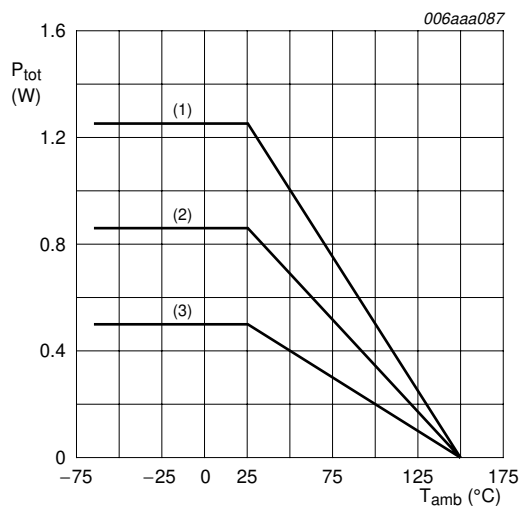
FR4 PCB, standard footprint

Fig 1. Power derating curve SOT54



- (1) FR4 PCB, mounting pad for collector 1 cm²
- (2) FR4 PCB, standard footprint

Fig 2. Power derating curves SOT223



- (1) FR4 PCB, mounting pad for collector 6 cm²
- (2) FR4 PCB, mounting pad for collector 1 cm²
- (3) FR4 PCB, standard footprint

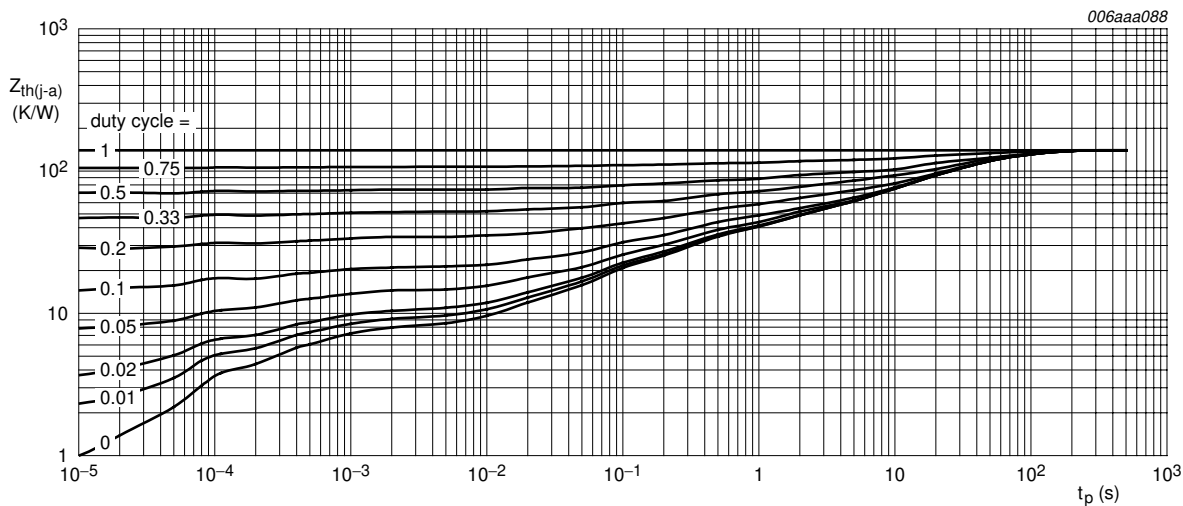
Fig 3. Power derating curves SOT89

6. Thermal characteristics

Table 7. Thermal characteristics

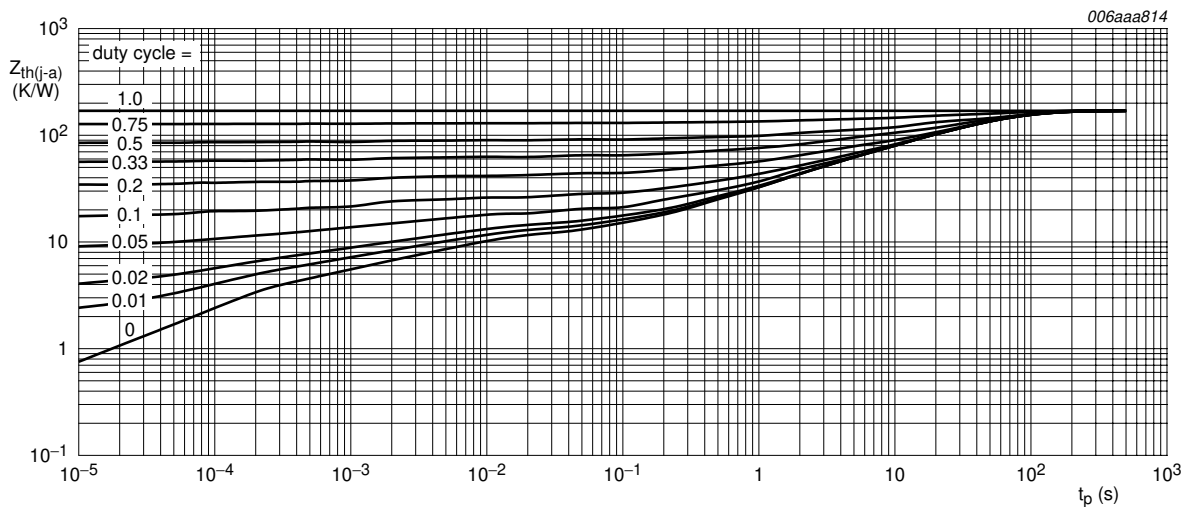
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	BC639	[1]	-	-	150	K/W
	BCP56	[1]	-	-	195	K/W
		[2]	-	-	130	K/W
	BCX56	[1]	-	-	250	K/W
		[2]	-	-	145	K/W
		[3]	-	-	100	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point					
	BC639		-	-	40	K/W
	BCP56		-	-	17	K/W
	BCX56		-	-	30	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².



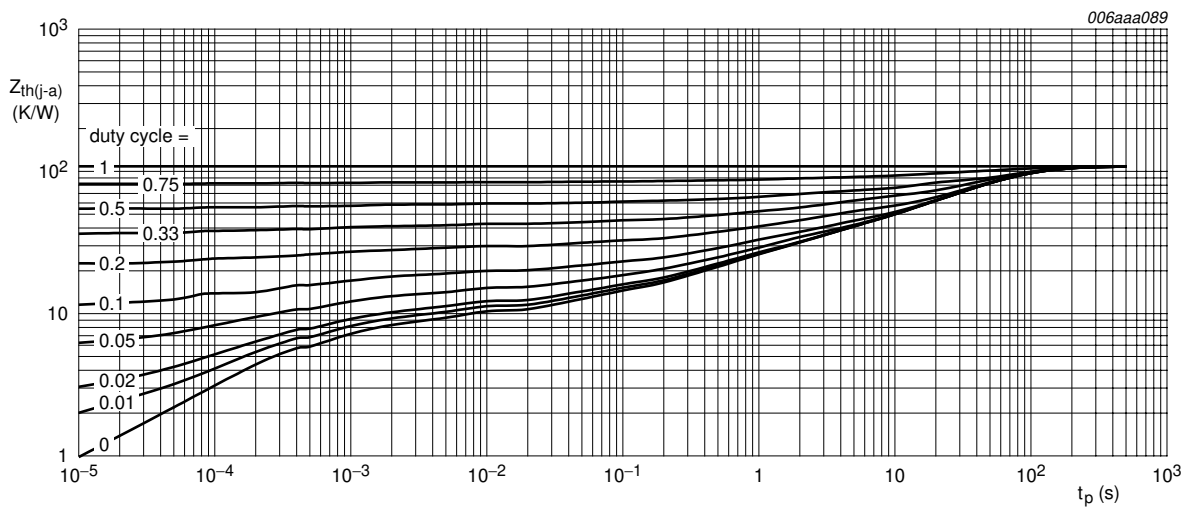
FR4 PCB, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT54; typical values



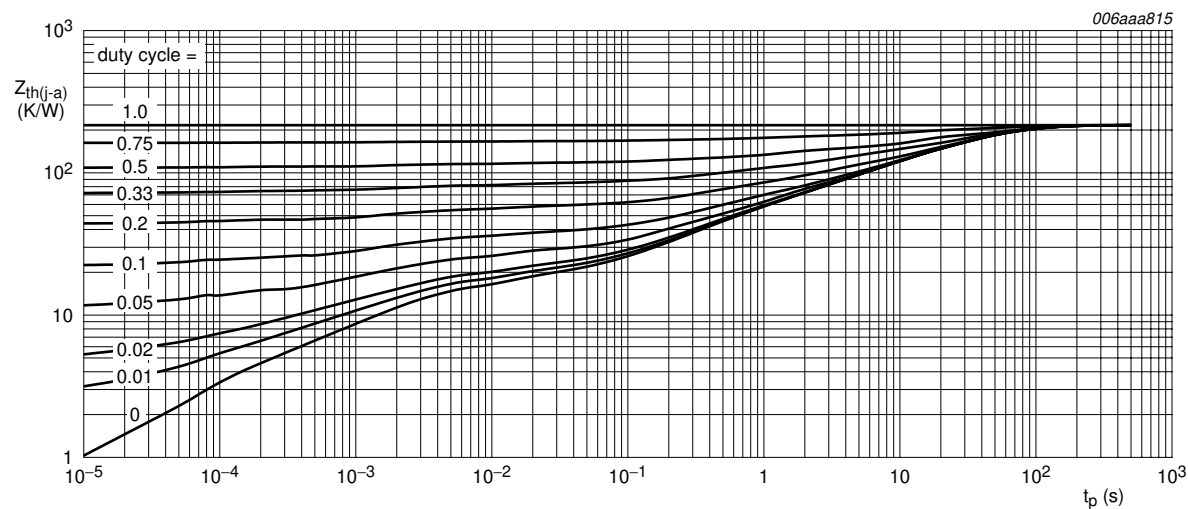
FR4 PCB, standard footprint

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



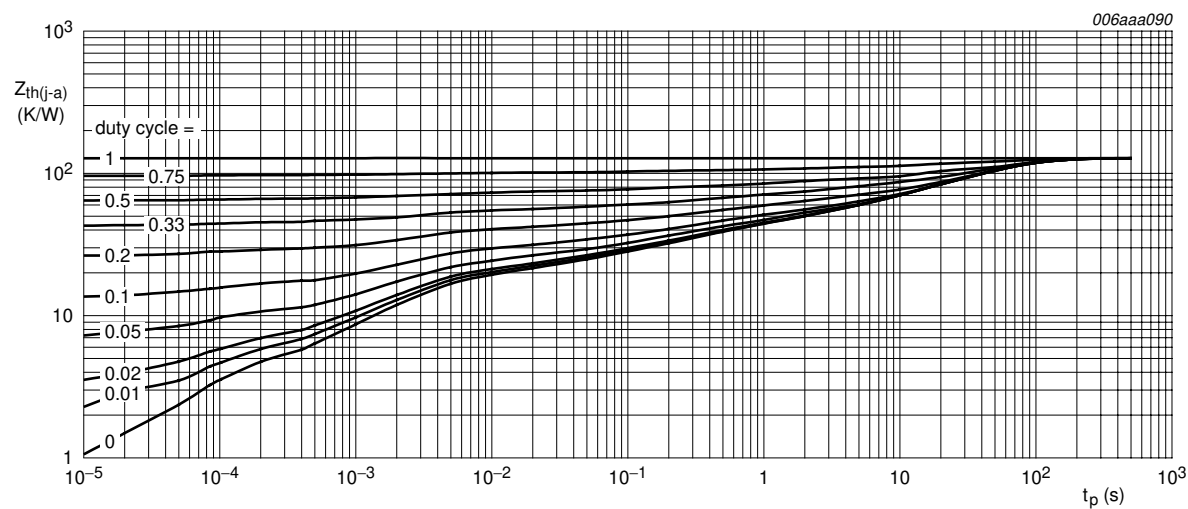
FR4 PCB, mounting pad for collector 1 cm²

Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, standard footprint

Fig 7. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values



FR4 PCB, mounting pad for collector 1 cm²

Fig 8. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

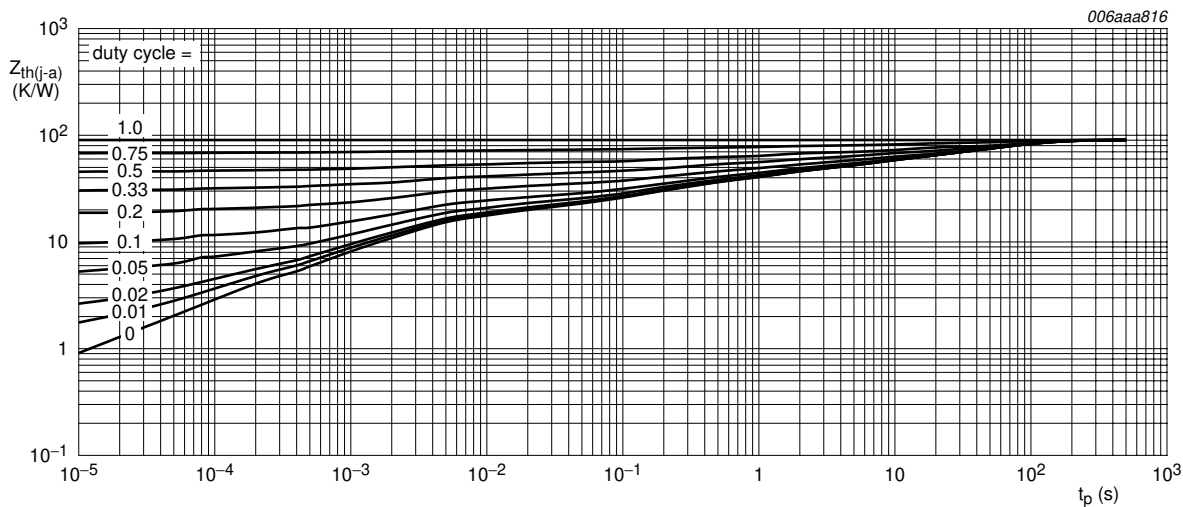


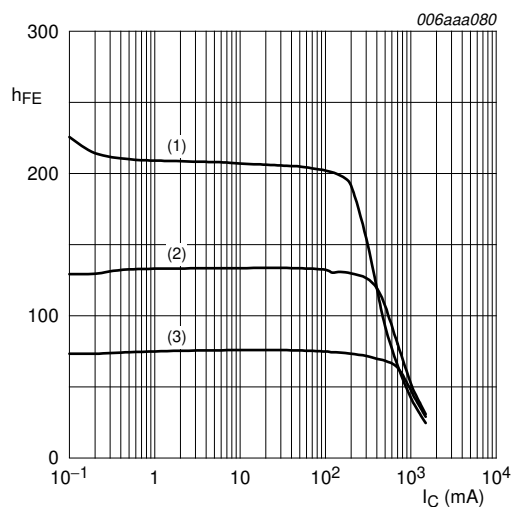
Fig 9. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

7. Characteristics

Table 8. Characteristics
Tamb = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ICBO	collector-base cut-off current	VCB = 30 V; IE = 0 A	-	-	100	nA
		VCB = 30 V; IE = 0 A; Tj = 150 °C	-	-	10	µA
IEBO	emitter-base cut-off current	VEB = 5 V; IC = 0 A	-	-	100	nA
hFE	DC current gain	VCE = 2 V				
		IC = 5 mA	63	-	-	
		IC = 150 mA	63	-	250	
		IC = 500 mA	[1] 40	-	-	
	DC current gain	VCE = 2 V				
	hFE selection -10	IC = 150 mA	63	-	160	
	hFE selection -16	IC = 150 mA	100	-	250	
VCEsat	collector-emitter saturation voltage	IC = 500 mA; IB = 50 mA	[1] -	-	500	mV
VBE	base-emitter voltage	VCE = 2 V; IC = 500 mA	[1] -	-	1	V
Cc	collector capacitance	VCB = 10 V; IE = ie = 0 A; f = 1 MHz	-	6	-	pF
fT	transition frequency	VCE = 5 V; IC = 50 mA; f = 100 MHz	100	180	-	MHz

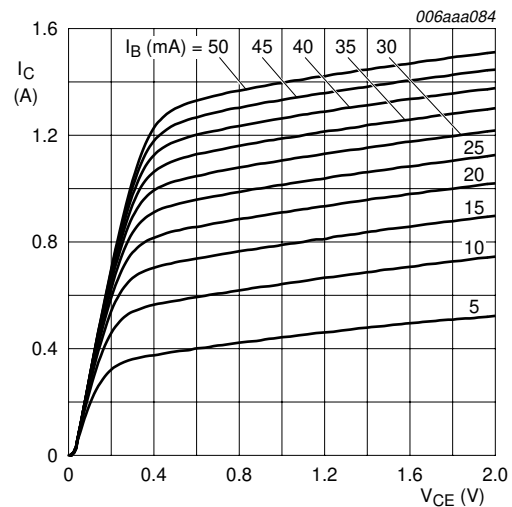
[1] Pulse test: tp ≤ 300 µs; δ = 0.02.



$V_{CE} = 2 \text{ V}$

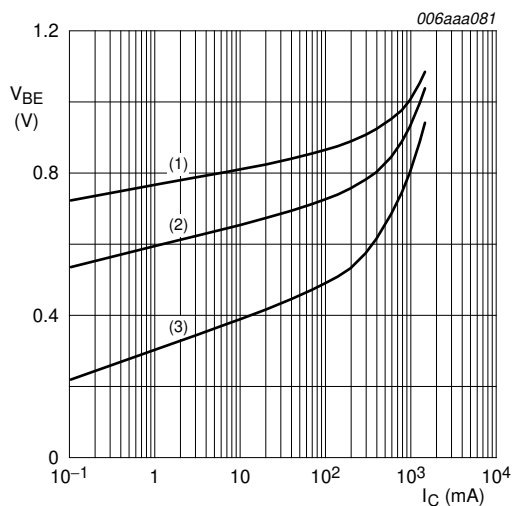
- (1) $T_{amb} = 150 \text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
- (3) $T_{amb} = -55 \text{ }^{\circ}\text{C}$

Fig 10. DC current gain as a function of collector current; typical values



$T_{amb} = 25 \text{ }^{\circ}\text{C}$

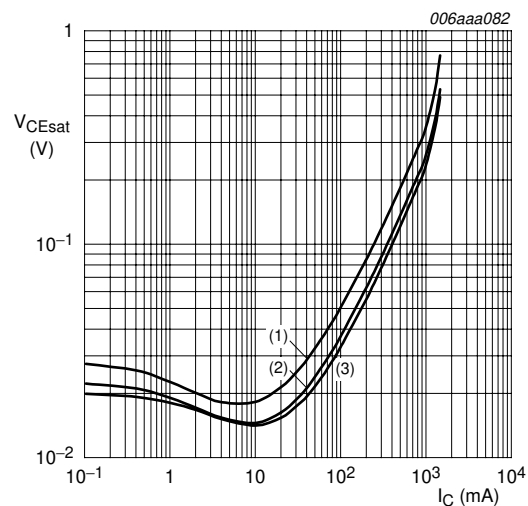
Fig 11. Collector current as a function of collector-emitter voltage; typical values



$V_{CE} = 2 \text{ V}$

- (1) $T_{amb} = -55 \text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 150 \text{ }^{\circ}\text{C}$

Fig 12. Base-emitter voltage as a function of collector current; typical values



$I_C/I_B = 10$

- (1) $T_{amb} = 150 \text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
- (3) $T_{amb} = -55 \text{ }^{\circ}\text{C}$

Fig 13. Collector-emitter saturation voltage as a function of collector current; typical values

8. Package outline

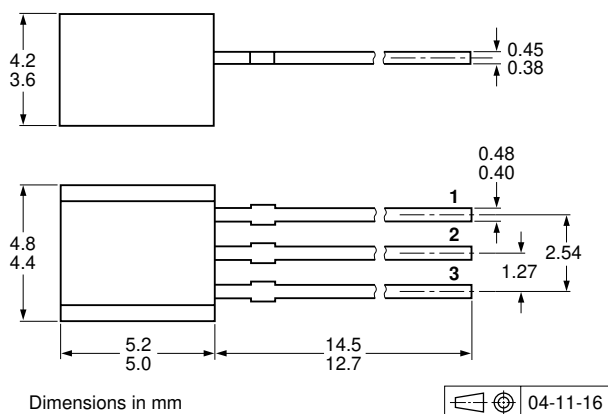


Fig 14. Package outline SOT54 (SC-43A/TO-92)

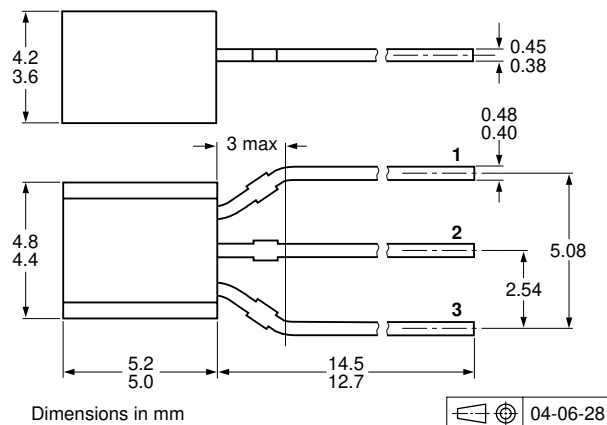


Fig 15. Package outline SOT54A

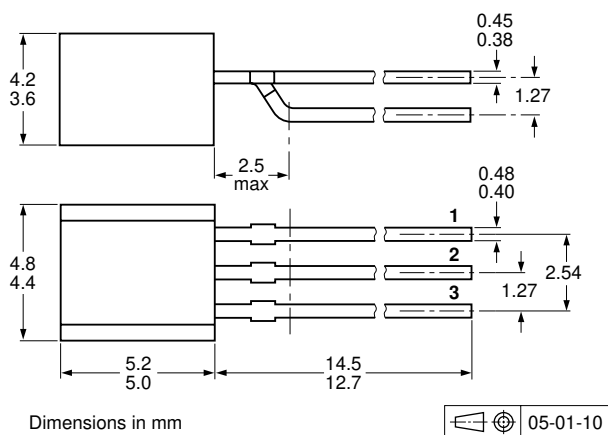


Fig 16. Package outline SOT54 variant

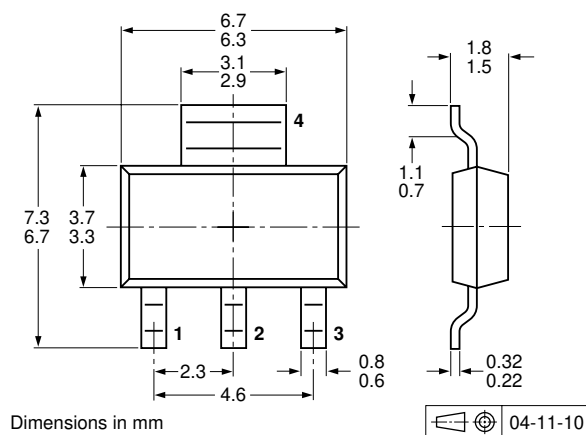


Fig 17. Package outline SOT223 (SC-73)

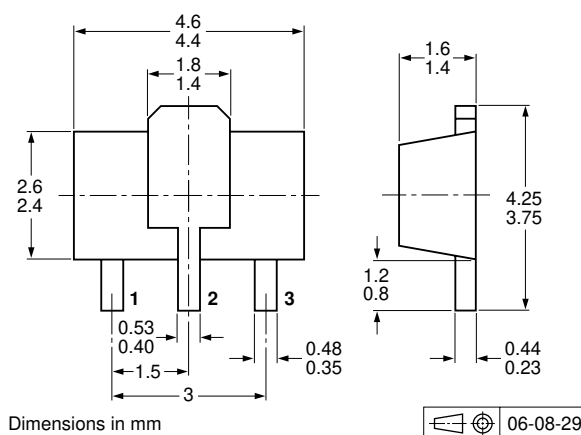


Fig 18. Package outline SOT89 (SC-62/TO-243)

9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number ^[2]	Package	Description	Packing quantity			
			1000	4000	5000	10000
BC639	SOT54	bulk, straight leads	-	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-	-116
		tape ammopack, wide pitch	-	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-	-112	-
BCP56	SOT223	8 mm pitch, 12 mm tape and reel	-115	-135	-	-
BCX56	SOT89	8 mm pitch, 12 mm tape and reel; T1 ^[3]	-115	-135	-	-
		8 mm pitch, 12 mm tape and reel; T3 ^[4]	-120	-	-	-

[1] For further information and the availability of packing methods, see [Section 12](#).

[2] Valid for all available selection groups.

[3] T1: normal taping

[4] T3: 90° rotated taping

10. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC639_BCP56_BCX56_8	20070622	Product data sheet	-	BC639_BCP56_BCX56_7
Modifications: • The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 1 “Product overview”: amended • Section 1.2 “Features”: amended • Section 1.3 “Applications”: amended • Table 2 “Quick reference data”: I_C parameter redefined to collector current • Table 2 “Quick reference data”: I_{CM} condition added • Figure 2 and 3: amended • Table 6 “Limiting values”: I_C parameter redefined to collector current • Table 6 “Limiting values”: I_{CM} condition added • Table 6 “Limiting values”: P_{tot} values for BCP56 and BCX56 adapted • Table 7 “Thermal characteristics”: R_{th(j-a)} values for BCP56 and BCX56 rounded • Figure 4: Z_{th} redefined to Z_{th(j-a)} transient thermal impedance from junction to ambient • Figure 4: t_p parameter redefined to pulse duration • Figure 5: added • Figure 6: Z_{th} redefined to Z_{th(j-a)} transient thermal impedance from junction to ambient • Figure 6: t_p parameter redefined to pulse duration • Figure 7: added • Figure 8: Z_{th} redefined to Z_{th(j-a)} transient thermal impedance from junction to ambient • Figure 8: t_p parameter redefined to pulse duration • Figure 9: added • Figure 11: amended • Table 9 “Packing methods”: new packing method for BCX56 added • Section 11 “Legal information”: updated				
BC639_BCP56_BCX56_7	20050308	Product data sheet	-	BC639_BCP56_BCX56_6
BC639_BCP56_BCX56_6	20050303	Product data sheet	CPCN200405029	BC635_637_639_4 BCP54_55_56_5 BCX54_55_56_4
BC635_637_639_4	20011010	Product specification	-	BC635_637_639_3
BCP54_55_56_5	20030206	Product specification	-	BCP54_55_56_4
BCX54_55_56_4	20011010	Product specification	-	BCX54_55_56_3

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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13. Contents

1 Product profile 1

1.1 General description..... 1

1.2 Features 1

1.3 Applications 1

1.4 Quick reference data..... 1

2 Pinning information..... 2

3 Ordering information..... 3

4 Marking..... 3

5 Limiting values..... 4

6 Thermal characteristics..... 6

7 Characteristics..... 9

8 Package outline 11

9 Packing information..... 12

10 Revision history..... 13

11 Legal information..... 14

11.1 Data sheet status 14

11.2 Definitions..... 14

11.3 Disclaimers..... 14

11.4 Trademarks..... 14

12 Contact information..... 14

13 Contents 15



Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.